

APPLICANT'S INFORMATION
DISCLOSURE STATEMENT

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Serial No.: To be assigned

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Applicant: Brodsky

Filing Date: Herewith

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Group:

2833

U.S. PATENT DOCUMENTS

Initial*		Document No.	Date	Name	Class	Subcl.	Filing Date
LG	AA	4,988,306	01/29/91	Hopfer, III et al	439	66	05/16/89
LG	AB	5,122,067	06/16/92	Sunne	439	91	05/23/91
LG	AC	5,599,193	02/04/97	Crotzer	439	66	08/23/94
LG	AD	5,650,919	07/22/97	Loh et al	361	779	02/21/96
LG	AE	5,720,630	02/24/98	Richmond et al	439	591	02/26/96
LG	AF	5,886,590	03/23/99	Quan et al	333	33	09/04/97
LG	AG	5,899,757	05/04/99	Neidich et al	439	67	11/03/97
LG	AH	5,939,783	08/17/99	Laine et al	257	702	05/05/98
LG	AI	5,940,278	08/17/99	Schumacher	361	769	04/30/97
LG	AJ	5,969,953	10/19/99	Purdum et al	361	790	09/23/98
LG	AK	6,036,502	03/14/00	Neidich et al	439	67	01/28/99

FOREIGN REFERENCES

	AL					
	AM					
	AN					
	AO					

OTHER DOCUMENTS

	AO	IBM Technical Disclosure Bulletin, January, 1993, "Button Contacts for Probe Card Applications", pp. 186-187
LG	AP	IBM Technical Disclosure Bulletin, March, 1991, "Pluggable/Removable Cube of Chips Packaging Method", pp. 459-460
	AQ	
	AR	
	AS	
	AT	

Examiner:

Meyumbe

Date Considered:

4/25/05

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if in conformance and not considered. Include copy of this form with next communication to applicant.